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STMicroelectronics STA510FTR

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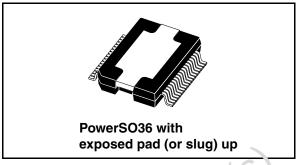
### 44-V, 5.5-A, quad power half bridge

#### **Features**

- Minimum input output pulse width distortion
- 150 mW Rdson complementary DMOS output stage
- CMOS compatible logic inputs
- Thermal protection
- thermal warning output
- Under-voltage protection
- No power-on, power- off sequence required

### **Description**

STA510F is a monolithic, quad, half-bridge stage in Multipower BCD technology. The device can be used as dual bridge or reconfigured, by connecting CONFIG pin to Vdd pin, as single bridge with double current capability, and as half bridge (binary mode) with half current capability.



The device is particularly designed to make the output stage of a stereo all-digital high efficiency (FFX) amplifier capable of delivering 100 W + 100 W output power into 8-Q loads with THD = 10% and  $V_{cc}$  = 39  $\frac{1}{2}$  In single BTL configuration the device can delive 200 W into a 4- $\Omega$  load with THD = 10% and  $\frac{1}{2}$  = 39 V.

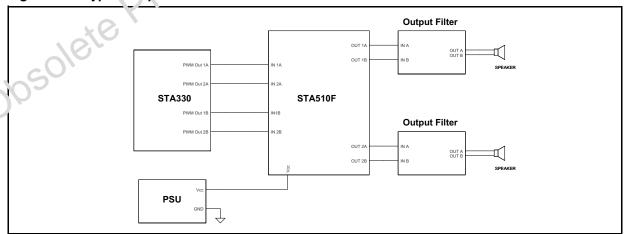
The device is fully compatible with the DDX® driver de rice.

The imput pins have a threshold proportional to  $V_L$  pin voltage.

Table 1. Device summary

Order code	Operating Tomp. range	Package	Packing
STA510F	0° to 70 C	PowerSO36 (slug up)	Tube

Figure 1. Typica! ລຽງໂຄວລtion



December 2007 Rev 1 1/11



Pin description STA510F

## 1 Pin description

Figure 2. Pin connection (top view)

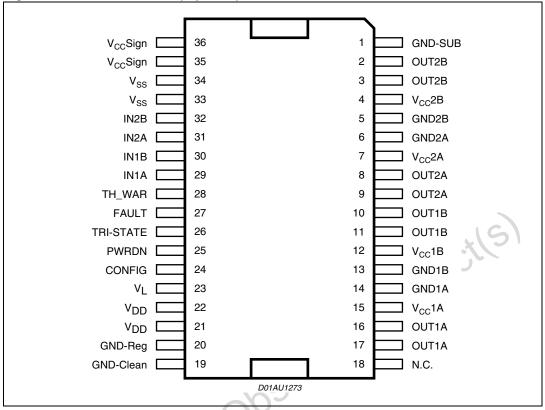


Table 2. Pin list

	Pin	Name	Description
	1	GND-SUB	Substrate ground
	2, 3	OUT2B	Output half bridge 2B
	4	Vcc2B	Positive Supply
	5	GND2B	Negative Supply
	6	GND2A	Negative Supply
	7	Vcc2A	Positive Supply
1050	8, 9	OUT2A	Output half bridge 2A
Oh	10, 11	OUT1B	Output half bridge 1B
	12	Vcc1B	Positive Supply
	13	GND1B	Negative Supply
	14	GND1A	Negative Supply
	15	Vcc1A	Positive Supply
	16, 17	OUT1A	Output half bridge 1A





**STA510F** Pin description

Table 2. Pin list (continued)

Pin	Name	Description		
18	NC	Not connected		
19	GND-clean	Logical ground		
20	GND-Reg	Ground for regulator Vdd		
21, 22	Vdd	5V Regulator referred to ground		
23	V <sub>L</sub>	High logical state setting voltage		
24	CONFIG	Configuration		
25	PWRDN	Stand-by		
26	TRI-STATE	Hi-Z		
27	FAULT	Fault pin advisor		
28	TH-WAR	Thermal warning advisor		
29	IN1A	Input of half bridge 1A		
30	IN1B	Input of half bridge 1B		
31	IN2A	Input of half bridge 2A		
32	IN2B	Input of half bridge 2B		
33, 34	Vss	5-V regulator referred to +Vcc		
35, 36	VCCSIGN	Signal positive supply		

### Table 3.

Pin	Logical value	Device status
FAULT (1)	0	Fault detected (short circuit, or thermal)
PAOLI	1	Normal operation
TRI-STATE	0 10	All power stages in Hi-Z state
INI-STATE	1	Normal operation
PWRDN	0	Low-power mode
FWHDIN	j	Normal operation
THWAR (1)	0	Temperature of the IC =130° C
IIIWAN * /	1	Normal operation
9	0	Normal Operation
CONFIG (2)	1	OUT1A = OUT1B, OUT2A = OUT2B (IF IN1A = IN1B and IN2A = IN2B)
1. The pin is ope	n collector. To have	e the high logic value, it needs a pull-up resistor.

- 1. The pin is open collector. To have the high logic value, it needs a pull-up resistor.
- 2. CONFIG = 1 means connect Pin 24 (CONFIG) to Pins 21, 22 (Vdd).

#### **Electrical specifications**

**STA510F** 

## 2 Electrical specifications

### 2.1 Absolute maximum ratings

Table 4. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	DC supply voltage (Pin 4, 7, 12, 15)	44	V
V <sub>max</sub>	Maximum voltage on pins 23 to 32	5.5	V
ESD	Max ESD on pins (HBM)	±1000	V
T <sub>op</sub>	Operating temperature range	0 to 70	° C
T <sub>stg</sub> , T <sub>j</sub>	Storage and junction temperature	-40 to 150	° C

### 2.2 Thermal data

Table 5. Thermal data

Symbol	Parameter	Min	Тур	Max	Unit
T <sub>j-case</sub>	Thermal resistance junction to case (thermal pad)		1	2.5	°C/W
T <sub>jSD</sub>	Thermal shut-down junction temperature		150		° C
T <sub>warn</sub>	Thermal warning temperature		130		° C
t <sub>hSD</sub>	Thermal shut-down hysteresis		25		° C

## 2.3 Electrical specifications

Unless otherwise stated, the results in *Table 6* below are given for the conditions:  $V_L = 3.3 \text{ V}$ , Vcc = 37 V and  $T = 25^{\circ} \text{ C}$  unless otherwise specified.

Table 6. Electrical specifications

	Symbol	Parameter	Condition	Min	Тур	Max	Unit
Obsole	R <sub>dsON</sub>	Power Pchannel/Nchannel MOSFET RdsON	ld = 1 A		150	200	mΩ
	I <sub>dss</sub>	Power Pchannel/Nchannel leakage current				100	μА
	g <sub>N</sub>	Power Pchannel RdsON matching	Id = 1 A	95			%
	g <sub>P</sub>	Power Nchannel RdsON matching	ld = 1 A	95			%
	Dt_s	Low current dead time (static)	see test circuit Figure 3		10	20	ns
	Dt_d	High current dead time (dynamic)	L=22 $\mu$ H, C = 470nF, R <sub>L</sub> = 8 $\Omega$ , Id = 4.5 A, see test circuit <i>Figure 4</i>			50	ns





#### **Electrical specifications**

#### Table 6. Electrical specifications (continued)

	Symbol	Parameter	Condition	Min	Тур	Max	Unit
	t <sub>d ON</sub>	Turn-on delay time	Resistive load			100	ns
	t <sub>d OFF</sub>	Turn-off delay time	Resistive load			100	ns
	t <sub>r</sub>	Rise time	Resistive load, as Figure 4			25	ns
	t <sub>f</sub>	Fall time	Resistive load, as Figure 4			25	ns
	V <sub>CC</sub>	Supply voltage operating voltage		10		40	٧
	V <sub>IN-High</sub>	High level input voltage		V <sub>L</sub> /2 +300 mV			V
	V <sub>IN-Low</sub>	Low level input voltage				V <sub>L</sub> /2 - 300m V	<b>v</b>
	I <sub>IN-H</sub>	High level input current	Pin voltage = V <sub>L</sub>		1	16	μΑ
	I <sub>IN-L</sub>	Low level input current	Pin voltage = 0.3V		1 (		μΑ
	I <sub>PWRDN-H</sub>	High level PWRDN pin input current	V <sub>L</sub> = 3.3V		35		μА
	$V_{Low}$	Low logical state voltage (pins PWRDN, TRISTATE) (see <i>Table 7</i> )	V <sub>L</sub> = 3.3V			0.8	٧
	$V_{High}$	High logical state voltage (pins PWRDN, TRISTATE) (see <i>Table 7</i> )	V <sub>L</sub> = 3.3V	1.7			V
	I <sub>VCC</sub> - PWRDN	Supply current from Vcc in power down	PWRDN = 0			3	mA
	I <sub>FAULT</sub>	Output current pins FAULT -TH-WARN when FAULT CONDITIONS	Vpin = 3.3V		1		mA
	I <sub>VCC-hiz</sub>	Supply current from Vcc in tri- state	Pin TRI-STATE = 0		22		mA
Obsole	lvcc	Supply current from Vcc in operation both channel switching)	Input pulse width duty cycle = 50%, switching frequency = 384 kHz, no LC filters;		70		mA
Oh	I <sub>OUT-SH</sub>	Overcurrent protection threshold Isc (short circuit current limit) (note 2)		5.5	7	9	Α
	V <sub>UV</sub>	Undervoltage protection threshold			7		V
	t <sub>pw_min</sub>	Output minimum pulse width	No Load	25		40	ns





#### **Electrical specifications**

STA510F

Table 7. V<sub>low</sub>, V<sub>high</sub> threshold variation with V<sub>L</sub>

V <sub>L</sub>	V <sub>Low</sub> max	V <sub>High</sub> min	Unit
2.7	0.7	1.5	V
3.3	0.8	1.7	V
5	0.85	1.85	V

Logic truth table Table 8.

•							
TRI-STATE	INxA	INxB	Q1	Q2	Q3	Q4	Output mode
0	х	х	OFF	OFF	OFF	OFF	Hi-Z
1	0	0	OFF	OFF	ON	ON	DUMP
1	0	1	OFF	ON	ON	OFF	NEGATIVE
1	1	0	ON	OFF	OFF	ON	POSITIVE
1	1	1	ON	ON	OFF	OFF	Not used

Figure 3. Test circuit for low current dead time

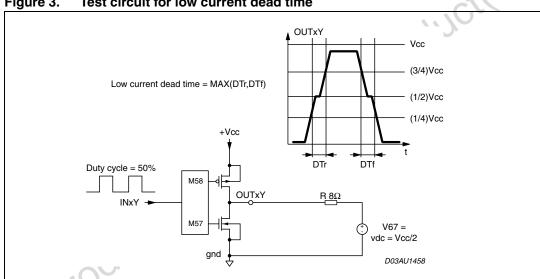
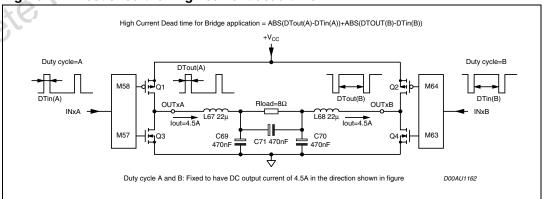


Figure 4. Test circuit for high current dead time



**Electrical specifications** 

Figure 5. Typical quad half-bridge configuration giving 200 W per channel into 4  $\Omega$  speakers, 10% THD,  $V_{CC}$  = 39 V

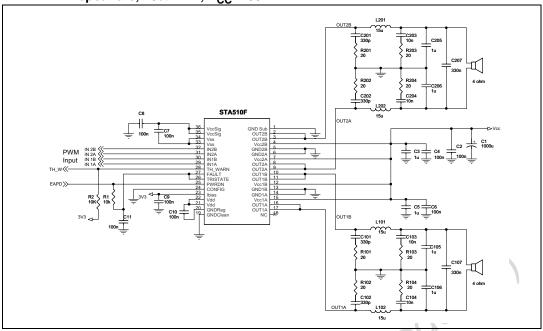
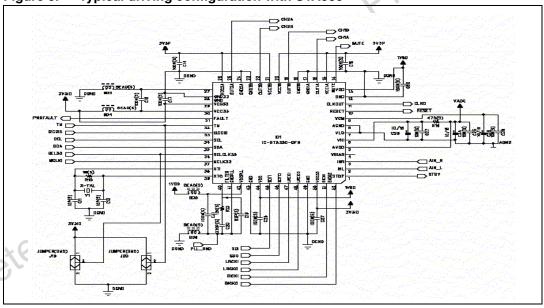


Figure 6. Typical driving configuration with STA330





Package information STA510F

## 3 Package information

In order to meet environmental requirements, ST offers these devices in ECOPACK<sup>®</sup> packages. These packages have a Lead-free second level interconnect. The category of second Level Interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark.

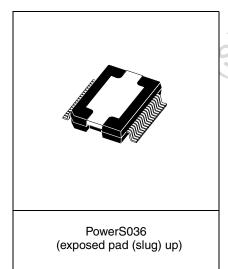
ECOPACK specifications are available at: http://www.st.com.

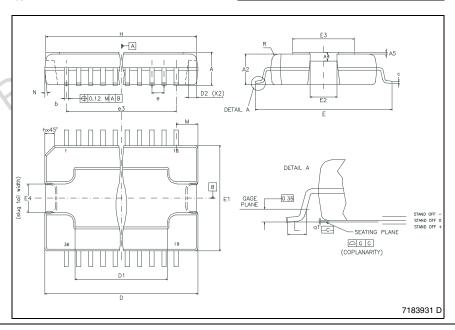
Figure 7. PowerSO36 package dimensions

DIM.		mm			inch	
DIM.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
Α	3.25		3.43	0.128		0.135
A2	3.1		3.2	0.122		0.126
A4	0.8		1	0.031		0.039
A5		0.2			0.008	
a1	0.030		-0.040	0.0011		-0.0015
b	0.22		0.38	0.008		0.015
С	0.23		0.32	0.009		0.012
D	15.8		16	0.622		0.630
D1	9.4		9.8	0.37		0.38
D2		1			0.039	
E	13.9		14.5	0.547		0.57
E1	10.9		11.1	0.429		0.437
E2			2.9			0.114
E3	5.8		6.2	0.228		0.244
E4	2.9		3.2	0.114		1.259
е		0.65			0.026	
e3		11.05			0.435	
G	0		0.075	0		0.003
Н	15.5		15.9	0.61		0.625
h			1.1			0.043
L	8.0		1.1	0.031		0.043
N			10°			10°
s			8 °			8°

<sup>(1) &</sup>quot;D and E1" do not include mold flash or protusions. Mold flash or protusions shall not exceed 0.15mm (0.006") (2) No intrusion allowed inwards the leads.

Outline and mechanical data









Trademarks and other acknowledgements

## 4 Trademarks and other acknowledgements

FFX is a STMicroelectronics proprietary digital modulation technology.

Obsolete Product(s). Obsolete Product(s)

DDX is a registered trademark of Apogee Technology, Inc.

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Revision history STA510F

## 5 Revision history

Table 9. Document revision history

Date	Revision	Changes
13-Dec-2007	1	Initial release.



# **Distributor of STMicroelectronics: Excellent Integrated System Limited**Datasheet of STA510FTR - IC QUAD HALF BRIDGE AMP PWRSO36

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#### STA510F

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